

REMARKS

The Examiner's allowance of claims 38 and 40-42 is acknowledged and appreciated.

Claims 7 and 10 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite. These claims have been amended in a readily apparent manner to overcome this rejection. Withdrawal of the rejection is respectfully requested.

Claims 1, 2, 5, 6, 8, 10, 30, 32-34 and 36-37 stand rejected under 35 U.S.C. §102(b) as being anticipated by Tsuda et al. (US 6,262,783). Applicants respectfully traverse this rejection.

Claim 1 has been amended to incorporate features described in claim 38, which has been allowed. Accordingly, claim 1 is now also believed to be allowable.

Independent claims 2, 8, 30 and 34 have been amended to more clearly describe the feature for heat treating the photo-sensitive resin layer to form undulation at the surface of the photo-sensitive resin layer and in the region having the distribution of thermal deformation characteristics. The Tsuda et al. reference, in Fig. 4A, discloses irradiating exposure energy to a resist 420 from the back surface of a plate 201 using common electrodes 205 as a mask, thereby leaving the resist 420 only in the portions protected by the common electrodes 205. The remaining resist 420 is then rounded by heat treatment. Thus, the Tsuda et al. reference does not employ thermal deformation characteristics distribution of resist in forming undulations on the resist.

In the present invention, the undulation is formed at the surface of the resin layer and in the region having the distribution of thermal deformation characteristics. In Tsuda et al., the surface of the resin layer is washed away except above the common electrodes 205. The portion of the resin layer remaining above the common electrode, however, does not have the distribution of thermal deformation characteristics. Accordingly, the Tsuda et al. reference does not disclose or suggest forming undulation at the surface of the photo-sensitive resin layer, and in the region having the distribution of thermal deformation characteristics, as in the present invention. For these reasons, claims 1, 2, 8, 30 and 34 are allowable over Tsuda et al.


Claims 1, 2, 6, 30, 32-34 and 36-37 stand rejected under 35 U.S.C. §102(b) as being anticipated by Tsuda et al. (US 6,600,535). Applicants respectfully traverse this rejection for the reasons given above traversing the rejection of the Tsuda et al. '783 reference. Claims 6, 32, and 36-37 depend from their respective independent claims 2, 30 and 34 and are also allowable for the same reasons, and because of the additional features that they recite.

Claim 11 stands rejected under 35 U.S.C. §103 (a) as being unpatentable over Tsuda et al. (US 6,262,783) in view of Fujioka et al. Applicants respectfully traverse this rejection for the same reasons given with respect to claim 8, from which claim 11 depends, and because of the additional features recited in claim 11.

For all of the above reasons, Applicants request reconsideration and allowance of the claimed invention. The Examiner should contact Applicants' undersigned attorney if a telephone conference would expedite prosecution.

Respectfully submitted,

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